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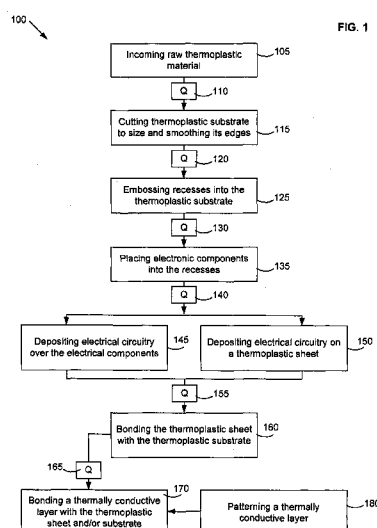
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(54) Title: ELECTRONIC DEVICE IN PLASTIC



(57) Abstract: The invention concerns a method for forming an electronic device in plastic. The method for forming an electronic device in plastic comprises: (a) placing electronic components (220, 215) in recesses (210, 215) in a thermoplastic substrate (200); (b) depositing (135) an electronic circuit (230) over the electronic components (220, 225), or onto a thermoplastic sheet (240); and (c) bonding (160) the thermoplastic substrate (200) with the thermoplastic sheet (240) in a thermal bonding process to seal the electronic components (220, 215) and the electronic circuit (230) between the thermoplastic substrate (200) and the thermoplastic sheet (240), wherein the method further comprises providing a thermally conductive layer (250) on the thermoplastic sheet (240) and/or substrate (200) such that heat applied during the thermal bonding process is distributed uniformly across the thermoplastic sheet (240) and/or substrate (200) to facilitate bonding of the thermoplastic sheet (240) and substrate (200). In another aspect, the invention concerns an electronic device formed according to the method. It is an advantage that a more uniform heat distribution is achieved.